



DATE: 13 March, 2024

PCN #: 2660

PCN Title: Qualification of Additional Wafer Source with Wafer Diameter and Mold Compound Changes for Select Discrete Products

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request immediately. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE

PCN-2660 REV 1

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
13 March, 2024	13 June, 2024	Discrete Automotive	Wafer Fab Material, Assembly Material	2660
TITLE				
Qualification of Additional Wafer Source with Wafer Diameter and Mold Compound Changes for Select Discrete Products				
DESCRIPTION OF CHANGE				
This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes Incorporated has qualified Diodes internal wafer fabrication source (GFAB) in Greenock, Scotland and Diodes internal wafer fabrication source (SFAB2) in Shanghai, China as additional wafer sources with wafer diameter being changed from 6 inch to 8 inch for select discrete products listed below. In addition, Diodes Incorporated has also qualified the following changes. - Internal "Diodes Technology (Cheng Du) Company Limited" (CAT) for back metal (BM) process for all affected parts. - Wafer top metal change from TiNiAg to NiAu at CAT for select products. - Mold compound type changes from nongreen to green or green to green at the existing assembly and test site for select products. Full electrical characterization and reliability testing has been completed on the representative part numbers to ensure there is no change to product reliability, device functionality or electrical specifications in the datasheet. There will be no change to the Form, Fit, or Function of affected products.				
IMPACT				
No change in datasheet parameters and product performance				
PRODUCTS AFFECTED				
Table 1 - Affected part list to add GFAB as additional wafer source and add CAT for BM				
Table 2 – Affected part list to add SFAB2 as additional wafer source, add CAT for BM, and change wafer diameter from 6 inch to 8 inch				
Table 3 – Affected part list to add SFAB2 as additional wafer source and add CAT for BM				
WEB LINKS				
Manufacturer’s Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/			
For More Information Contact:	https://www.diodes.com/about/contact-us/contact-sales/			
Data Sheet:	https://www.diodes.com/catalog/			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				

Table 1 - Affected part list to add GFAB as additional wafer source and add CAT for BM

BAT40V-7	SDM03MT40A-7-F	SDM10U45LP-7	SDMG0340L-7-F	SDMG0340LS-7-F	SDMP0340LCT-7-F
BAT54S-7-G	SDM03U40-7	SDM20U40-13	SDMG0340LA-7-F	SDMK0340L-7-F	SDMP0340LST-7-F
BAT54WS-7-G	SDM10M45SD-7-F	SDM20U40-7	SDMG0340LC-7-F	SDMP0340LAT-7-F	SDMP0340LT-7-F
SDM03MT40-7-F	SDM10U45-7				

Table 2 - Affected part list to add SFAB2 as additional wafer source, add CAT for BM, and change wafer diameter from 6 inch to 8 inch

SBR0240LPW-7B	SBR10U150CTFP**	SBR20A200CT**	SBR2A30P1-7*	SBR3060CTFP	SBR3U60P1-13*
SBR0330CW-7	SBR10U200CT**	SBR20A200CTB	SBR2A40P1-7*	SBR30A100CTFP**	SBR3U60P1-7*
SBR10200CT**	SBR10U200CTB-13-G	SBR20A200CTB-13	SBR2A40SA-13*	SBR30A40CTFP	SBR4060CTFP
SBR10200CTB	SBR10U200CTFP**	SBR20A200CTB-13-G	SBR2M30P1-7*	SBR30A60CTFP	SBR40U150CT-G***
SBR10200CTB-13-G	SBR10U200CTFP-G***	SBR20A200CTFP**	SBR2M60S1F-7*	SBR30A60CTFP-G	SBR40U200CT**
SBR10200CTFP**	SBR10U60CTFP	SBR20A200CTFP-G***	SBR2U100LP-7	SBR3A40SA-13*	SBR40U200CTB
SBR10200CTFP-G***	SBR1A20T5-7	SBR20A200CT-G***	SBR2U30SA-13*	SBR3A40SAF-13*	SBR40U200CTB-13
SBR10200CT-G***	SBR1A30T5-7	SBR20A60CTFP	SBR2U60S1F-7*	SBR3M30P1-7*	SBR4U130LP-7
SBR10200CTL-13	SBR20150CT**	SBR20U100CTFP-G***	SBR30200CT**	SBR3U150LP-7	SBR545SAF-13*
SBR10U100CTFP**	SBR20150CTFP-G***	SBR20U150CT**	SBR30200CTFP**	SBR3U20SA-13*	SBR60A200CT**
SBR10U100CTFP-G***	SBR2060CTFP-G	SBR20U150CT-G***	SBR30200CTFP-G***	SBR3U40P1-7*	SBR6200CTL-13
SBR10U150CT**	SBR20A150CTFP**	SBR20U60CTFP-G	SBR30200CT-G***	SBR3U40S1F-7*	

Note: "*" Wafer Top Metal Change from TiNiAg to NiAu at CAT

"***" Change from Non-Green Mold Compound Type to Green Mold Compound Type in Assembly

"****" Change from Green Mold Compound Type to another Green Mold Compound Type in Assembly

Table 3 - Affected part list to add SFAB2 as additional wafer source and add CAT for BM,

SBR10100CTFP**	SBR10U200P5-13*	SBR2045CTFP	SBR20A45CTFP	SBR30A120CTFP**	SBR3U30P1-7*
SBR10150CT**	SBR10U200P5-13D*	SBR2045CTFP-G	SBR20U150CTFP**	SBR30A120CTFP-G***	SBR40100CTFP**
SBR10150CTE	SBR10U40CTFP	SBR20A100CTFP**	SBR2U30P1-7*	SBR30A150CT**	SBR40150CT***
SBR10150CTFP-G***	SBR1U200P1-7*	SBR20A100CTFP-G***	SBR30150CTFP-G***	SBR30A150CTFP**	SBR40150CTFP-G***
SBR10150CT-G***	SBR20100CTFP**	SBR20A150CT**	SBR30150CT-G***	SBR30A150CTFP-G***	SBR4040CTFP
SBR10150CTL-13	SBR20100CTFP-G***	SBR20A150CTFP-G***	SBR3040CTFP	SBR30A150CT-G***	SBR4045CTFP
SBR1060CTFP**	SBR20150CTFP**	SBR20A150CT-G***	SBR3045CTFP	SBR30A45CTFP-G	

Note: "*" Wafer Top Metal Change from TiNiAg to NiAu at CAT

"***" Change from Non-Green Mold Compound Type to Green Mold Compound Type in Assembly

"****" Change from Green Mold Compound Type to another Green Mold Compound Type in Assembly